# RD-ECR (Engineering Change Request)

申請人: 機構課/蔡豐禧　　表單號: 14　申請日期: 2026-06-10

| | | | | | |
|---|---|---|---|---|---|
| Proposed Change | ☐ Design modification 設計修改 ☐ Second source change 替代料變更<br>☑ Material change 材料變更 ☐ Manufacturer change 製造商變更<br>☐ Process sequency change 工序變更 ☐ Factory change 工廠變更<br>☐ Equipment/Tooling change 設備/模具變更<br>☐ Process/Method/Condition change 加工流程/方法 /條件變更 ☐ Others 其他 | | | EC No | EC26060601 |
| - | N/A | | | Initiator | 蔡豐禧(D0450) |
| Reason for Change | The aluminum extrusion die of the stand arm has worn down over the years, reducing the internal assembly space. Some slideway plates need to be removed to meet asse mbly requirements. | | | Issue Date | 2026-06-10 |
| Model / Part No | TSD-PT241W-C | | | Requester Dept | DV11R002-研發-機構課 |
| Implementation Type | ◉ 1. Immediately Change 立即切換 ○ 2. Running Change 自然切換<br>○ 3. Other 其他 | | | - | N/A |
| PM | 曹嘉雯(D0572) | Sales | 陳冠華(D0525) | Customer Approval | ○ Needed<br>◉ Not needed |
| File attached 附件上傳 | modify_contrast_drawing....<br>設計變更審查會議記錄_3M... | Customer Sign-off Area 客戶簽核 | | Customer Name | MEE |
| Comments 會簽意見 | 無在途工單需EC | | | | |

**Material Change Description 物料變更說明**

| No | Subassembly | T | PartNo | Description | Qty | Location | Stock | Remark |
|---|---|---|---|---|---|---|---|---|
| 1 | 2AADLK60022 | B | 3MDLNAME280 | SLIDEWAY PLATE (T) | 6.000 | | 1,392 | |
| 1 | 2AADLK60022 | A | | Delete | | | | |

**Engineering Change Assessment Item List 工程變更評估項目清單**

| | | |
|---|---|---|
| 1. Application for Revision of Specification or Drawing(s) for delivery 是否有修改交貨的規格或圖面 | 1.Confirm | ○ Yes ◉ No need |
| 2. Standards or Regulatories impact 是否有評估適用之標準或主管機關之相關法規的申請 | 2.Confirm | ○ Yes ◉ No need |
| 3. Change point of PCB mounting PCBA插件位置是否變更 | 3.Confirm | ○ Yes ◉ No need |
| 4. PCBA Process Changes PCBA製程是否變更 | 4.Confirm | ○ Yes (Continue checking below)<br>◉ No |
| _ 4-1) Change of Reflow temperature 迴焊溫度是否變更 | 4-1 Confirm | ○ Yes ◉ No need |
| _ 4-2) Change of bonding temperature 膠合溫度是否變更 | 4-2 Confirm | ○ Yes ◉ No need |
| _ 4-3) Change of Manual Soldering temperature 人工手焊工具之溫度是否變更 | 4-3 Confirm | ○ Yes ◉ No need |
| _ 4-4) Change of storage condition after protection humidity package 防潮包裝完成後的儲存條件是否變更 | 4-4 Confirm | ○ Yes ◉ No need |
| 5. Reliability test report(Test result and data) 是否有可靠性測試報告(測試結果及數據) | 5.Confirm | ○ Yes ◉ No need |
| 6. Process FMEA(Medical only) 是否有進行製程失效模式與效應分析 | 6.Confirm | ○ Yes ◉ No need |
| 7. Design FMEA(Medical only) 是否有進行設計失效模式與交應分析 | 7.Confirm | ○ Yes ◉ No need |
| 8. Risk Management(Medical only) 是否有進行風險管理評估 | 8.Confirm | ○ Yes ◉ No need |
| 9. Change points due to the modification 是否此修改會延伸導致其他變更點 | 9.Confirm | ○ Yes ◉ No need |
| 10. Initial Supply Control implements plan or result 是否有實施供料控制評估 | 10.Confirm | ○ Yes ◉ No need |
| _ 10-1) Confirm the work order or order number or date for the implementation start of the engineering change 確認工程變更開始實施之工單或訂單號碼或日期 | 10-1 Confirm | ○ Yes ◉ No need |
| _ 10-2) Coordinate the handling methods for related products and materials 協調相關產品及材料處理方法 | 10-2 Confirm | ○ Yes ◉ No need |
| _ 10-3) Arrange th production schedule 處理生產日程之安排 | 10-3 Confirm | ○ Yes ◉ No need |

| | | |
|---|---|---|
| _ 10-4) Control the changed materials 變更材料之管制 | 10-4 Confrim | ○ Yes ◉ No need |
| _ 10-5) Establish relevant execution control records for EC materials, register traceability data for each material 建立有關工程變更物料之相關執行管控記錄、登錄各項物料追溯性資料 | 10-5 Confirm | ◉ Yes ○ No need |
| 11. Training Requirement 若此一變更影響製程或檢驗，是否需要再做人員訓練 | 11.Confrim | ○ Yes ◉ No need |
| 12-1. Modification contents(For example, the following documents) 是否有評估此變更之各項相關文件(如下) | 12-1 Confirm | ☐ QC control plan<br>☐ Service Manual<br>☐ Others ☑ Not needed |
| 12-2. Modification contents(For example, the following documents) 是否有評估此變更之各項相關文件(如下) | 12-2 Confirm | ☐ SIP ☑ SOP<br>☐ Others ☐ No need |
| 12-3. Modification contents(For example, the following documents) 是否有評估此變更之各項相關文件(如下) | 12-3 Confirm | ☐ MDF ☐ DMR<br>☐ Approval Sheet<br>☐ Engineering Spec<br>☐ Others ☑ Not needed |
| DIVA 鈺緯科技開發股份有限公司 | 版本：C | 表單編號：QR-736-05 |

簽核列表 ◉ 表格 ○ 圖形

| 序號 | 簽核人 | 簽核結果 | 簽核意見 |
|---|---|---|---|
| 1 | **陳志偉**<br>二階主管(課/部級) | **同意**<br>2026-06-10 13:13 | |
| 2 | **廖榮棋**<br>DQE | **同意**<br>2026-06-10 13:46 | |
| 3 | **陳冠華**<br>Sales | **同意**<br>2026-06-10 16:40 | |
| 3 | **曹嘉雯**<br>PM | **同意**<br>2026-06-10 18:38 | |
| 4 | **楊建勛**<br>R&D Director [通知] | **同意**<br>2026-06-10 18:38 | [通知] |
| 5 | **蕭玉桃**<br>ECR-PIC人員 | **同意**<br>2026-06-11 10:42 | |
| 6 | **蔡豐禧**<br>申請人撤回 | **申請人撤回**<br>2026-06-11 14:06 | 工控機種, 風險管理計畫書不需勾選. |
| 7 | **陳志偉**<br>二階主管(課/部級) | **同意**<br>2026-06-11 14:17 | |
| 8 | **廖榮棋**<br>DQE | **同意**<br>2026-06-11 14:20 | |
| 9 | **曹嘉雯**<br>PM | **同意**<br>2026-06-12 11:55 | |
| 9 | **陳冠華**<br>Sales | **同意**<br>2026-06-12 15:54 | |
| 10 | **楊建勛**<br>R&D Director [通知] | **同意**<br>2026-06-12 15:54 | [通知] |
| 11 | **蕭玉桃**<br>ECR-PIC人員 | **同意**<br>2026-06-12 15:55 | |
| 12 | **王世炫**<br>ECR-PE人員 | **同意**<br>2026-06-15 08:42 | 2AADLK60022 BASE, 有單獨加工包裝SOP, TSD-PT241W-C_1A1A241621019OOSOP無影響. |
| 13 | **林益銓**<br>PE | **同意**<br>2026-06-16 08:40 | |
| 14 | **黃振哲**<br>ECR-PMC人員 | **同意**<br>2026-06-16 13:39 | |
| 15 | **邱羽萱**<br>PMC | **同意**<br>2026-06-16 14:14 | |
| 16 | **黃瓊玉**<br>ECR-PD人員 | **同意**<br>2026-06-16 14:29 | |

| 序號 | 簽核人 | 簽核結果 | 簽核意見 |
| --- | --- | --- | --- |
| 16 | **吳汶浦**<br>PD | **同意**<br>2026-06-17 13:36 | |
| 16 | **李慧珊**<br>ECR-SCM人員 | **同意**<br>2026-06-18 14:15 | |
| 17 | **呂姿葶**<br>[李慧珊 加簽] | **同意**<br>2026-06-18 14:54 | |
| 18 | **李金龍**<br>ECR-QA人員 | **同意**<br>2026-06-18 16:54 | |
| 19 | **陳泰盛**<br>QA | **同意**<br>2026-06-18 18:12 | |
| 20 | **楊建勛**<br>R&D Director | **同意**<br>2026-06-22 07:51 | |
| 21 | **蕭玉桃**<br>ECR-PIC人員 | **同意**<br>2026-06-22 15:07 | |
| 22 | **蔡豐禧**<br>SAP核發 | **同意**<br>2026-06-22 17:50 | |